

18. (New) The arrangement of claim 10, wherein the second chips comprise a transistor.

Alu
New
19. ~~(Allowable)~~ A circuit arrangement comprising:

- a power section, which comprises heat-generating components and at least one component producing less heat,
 - the component producing less heat being arranged in an internal region of the circuit arrangement, and
 - the heat-generating components being arranged around the internal region and being mounted on first and second metallic bodies acting as an electrical conductors, said bodies being electrically connected to the heat-generating components,
 - the bodies are arranged in an electrically insulating manner in the region of the heat-generating components on a heat sink, in order to cool the heat-generating components,
 - the heat sink running underneath the internal region of the circuit arrangement with the components producing less heat,
 - a third metallic body comprising a board covering the internal region and arranged above the component producing less heat,
 - the board comprising at least one opening above the internal region,
 - the component producing less heat being embodied as a capacitor and being electrically connected to the third metallic board via a first wired bond, which is led through the opening,
 - the heat-generating components being embodied as bare first and second chips, each containing a transistor and being mounted on the two metallic bodies, the first chips mounted on the first metallic body comprising a board, the second chips mounted on the second metallic body comprising a bar,
 - the first metallic body running along the outer edge of the heat sink,
 - the second metallic body covering the internal region and inner edge of the heat sink,
 - the first chips electrically connected to the first metallic body via bonding connections, and

- the second chips electrically connected to the second metallic body via bonding connections.

20. ^{dh}
^{New}
(~~Allowable~~) A circuit arrangement comprising:

- a power section, which comprises heat-generating components and at least one component producing less heat,
 - the component producing less heat being arranged in an internal region of the circuit arrangement, and
 - the heat-generating components being arranged around the internal region and being mounted on at least one metallic body acting as an electrical conductor, said body being electrically connected to the heat-generating components, wherein
 - the body is arranged in an electrically insulating manner in the region of the heat-generating components on a heat sink, in order to cool the heat-generating components,
 - the heat sink running underneath the internal region of the circuit arrangement with the components producing less heat,
 - a logic section, arranged above the internal region,
 - said logic section electrically connected to the power section via bonding connections.